TOSHIBA TLP818

## TOSHIBA PHOTO-INTERRUPTER INFRARED LED + PHOTOTRANSISTOR

# **TLP818**

BURNER MOTOR ROTATION DETECTOR FOR OIL FAN HEATERS

COIN PASS DETECTOR FOR VENDING MACHINES
PAPER PASS DETECTOR FOR TICKET VENDING
MACHINES

PAPER DETECTOR FOR PRINTERS AND FAX MACHINES

The TLP818 is a photo-interrupter with a dust-proof cover. It is not particularly prone to the adverse effects of dust since dust does not accumulate in the detection.

• Built-in dust-proof cover

• Snap-in mounting type (for 1.6 mm thick of PCBs)

• Gap : 5 mm

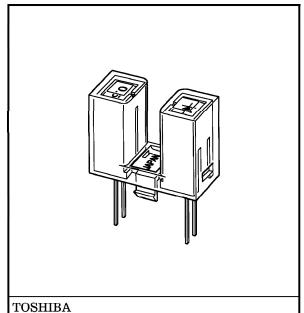
• Resolution : Slit width = 0.5 mm

• High current transfer ratio :  $I_C/I_F = 2.5\%$  (min)

• Fast response speed :  $t_r$ ,  $t_f = 6 \mu s$  (typ.)

• Device is not adversely affected by indoor lighting because detector is made of resin which is impermeable to visible light.

Package material : Polycarbonate

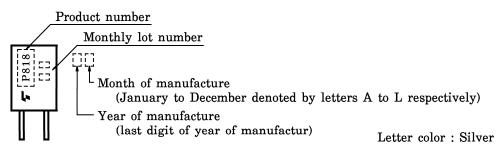


Weight: 1.29 g (typ.)

### MAXIMUM RATINGS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
LED	Forward Current	$I_{\mathbf{F}}$	50	mA	
	Forward Current Derating (Ta>25°C)	ΔI <sub>F</sub> /°C	-0.33	mA/°C	
	Reverse Voltage	$v_{R}$	5	V	
<u>~</u>	Collector-Emitter Voltage	VCEO	35	V	
CTOR	Emitter Collector Voltage	VECO	5	V	
CJ	Collector Power Dissipation	PC	75	mW	
DETE	Collector Power Dissipation Derating (Ta>25°C)	△P <sub>C</sub> /°C	-1	mW/°C	
	Collector Current	$I_{\mathbf{C}}$	50	mA	
Operating Temperature Range		$T_{ m opr}$	-25~85	°C	
Ste	orage Temperature	$T_{ m stg}$	-40~100	°C	

#### **MARKINGS**



# OPTICAL AND ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC		SYMBOL	TEST CONDITION	Min	Тур.	Max	UNIT
LED	Forward Voltage	$V_{\mathbf{F}}$	$I_{ m F}=10{ m mA}$	1.00	1.15	1.30	V
	Reverse Current	$I_{ m R}$	$V_R = 5 V$	_	_	10	$\mu$ <b>A</b>
	Peak Light Emission Wavelength	$\lambda_{\mathbf{P}}$	$ m I_{ m F}=10mA$		940		nm
DETECTOR	Dark Current	I <sub>D</sub> (I <sub>CEO</sub> )	$V_{ m CE} = 24 \  m V, \ I_{ m F} = 0$	_	_	0.1	$\mu$ A
	Peak Sensitivity Wavelength	$\lambda_{\mathbf{P}}$	_	1	870	1	nm
COUPLED	Current Transfer Ratio	$I_{\mathbf{C}}/I_{\mathbf{F}}$	$ m V_{CE} = 5~V,~I_{F} = 20~mA$	2.5	_	32	%
	Leakage Current	I <sub>LEAK</sub>	$V_{CE} = 5 \text{ V}, I_F = 50 \text{ mA}$ Shutter in		1	10	$\mu$ <b>A</b>
	Collector-Emitter Saturation Voltage	V <sub>CE</sub> (sat)	$I_{\mathrm{F}}=20\mathrm{mA},~I_{\mathrm{C}}=0.25\mathrm{mA}$		0.15	0.4	V
	Rise Time	t <sub>r</sub>	$V_{CC} = 5 V$ , $I_{C} = 2 mA$ ,		6		449
	Fall Time	$t_f$	$R_{\rm L} = 100  {\rm k}\Omega$	_	6	_	$\mu$ s

#### **PRECAUTIONS**

The following points must be borne in mind.

1. Soldering temperature: 260°C max

Soldering time: 5 s max

(Soldering must be performed 1.5 mm under the package body.)

2. Clean only the soldered part of the leads. Do not immerse the entire package in the cleaning solvent.

3. The package is made of polycarbonate. Polycarbonate is usually stable with acid, alcohol and aliphatic hydrocarbons, however, with petrochemicals (such as benzene, toluene and acetone), alkalis, aromatic hydrocarbons, or chloric hydrocarbons, polycarbonate may crack, swell or melt. Please take this into account when chosing a packaging material by refering to the table below.

<Chemicals which should not be used with polycarbonate>

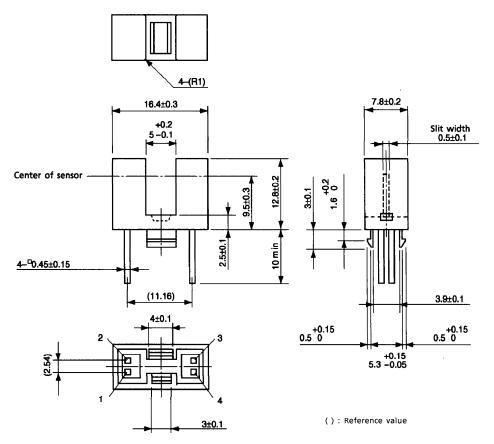
	PHENOMENON	CHEMICALS	
A	Staining and slight deterioration	Nitric acid (diluted), hydrogen peroxide, chlorine	
В	Cracking, crazed or swelling	<ul> <li>Acetic acid (70% or more)</li> <li>Gasoline</li> <li>Methyl ethyl ketone, ethyl acetate, butyl acetate</li> <li>Ethyl methacrylate, ethyl ether, MEK</li> <li>Acetone, m-amino alcohol, carbon tetrachloride</li> <li>Carbon disulfide, trichloroethylene, cresol</li> <li>Thinners, oil of turpentine</li> <li>Triethanolamine, TCP, TBP</li> </ul>	
С	Melting { }: Used as solvent	<ul> <li>Concentrated sulfuric acid</li> <li>Benzene</li> <li>Styrene, acrylonitrile, vinyl acetate</li> <li>Ethylenediamine, diethylenediamine</li> <li>[Chloroform, methyl chloride, tetrachloromethane, dioxane,]</li> <li>1, 2-dichloroethane</li> </ul>	
D	Decomposition	Ammonia water     Other alkalis	

- 4. Mount the device on a level surface.
- 5. This product has a dust-proof cover over the detection slit but does not have one on the underside.
- 6. Conversion efficiency falls over time due to the current which flows in the infrared LED. When designing a circuit, take into account this change in conversion efficiency over time. The ratio of fluctuation in conversion efficiency to fluctuation in infrared LED optical output is 1:1.

$$\frac{I_{C}/I_{F}(t)}{I_{C}/I_{F}(0)} = \frac{P_{O}(t)}{P_{O}(0)}$$

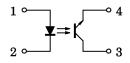
## PACKAGE DIMENSIONS

Unit: mm

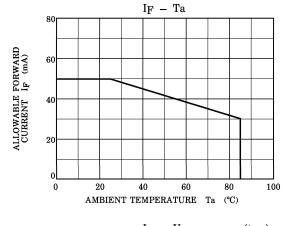


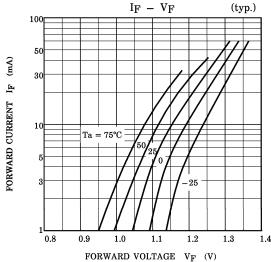
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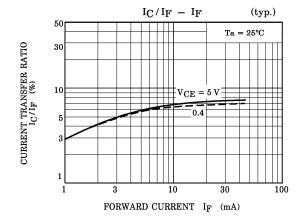
## PIN CONNECTION

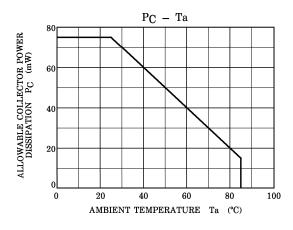


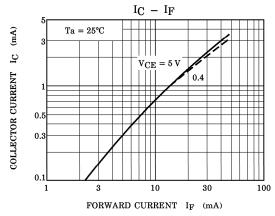
- 1. Anode
- 2. Cathode
- 3. Collector
- 4. Emitter

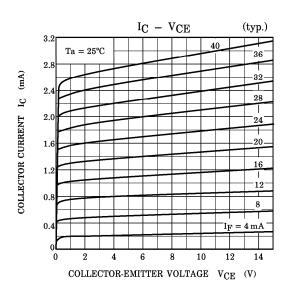


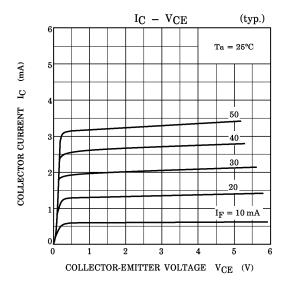


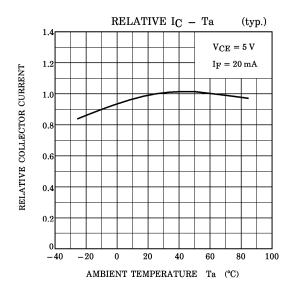


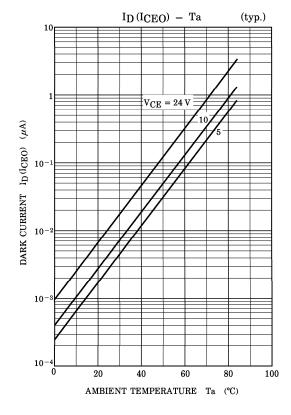


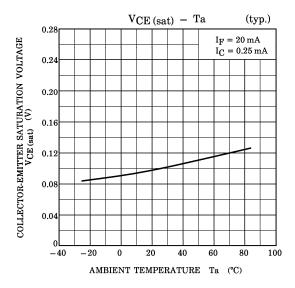


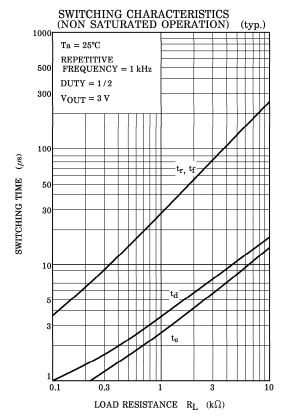


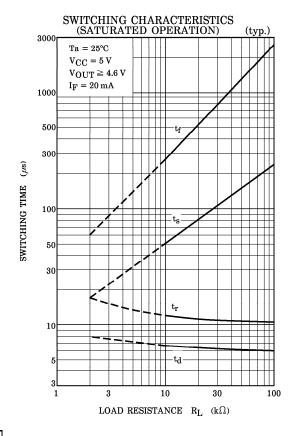


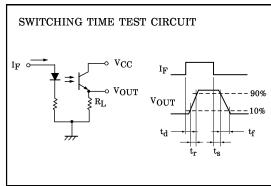




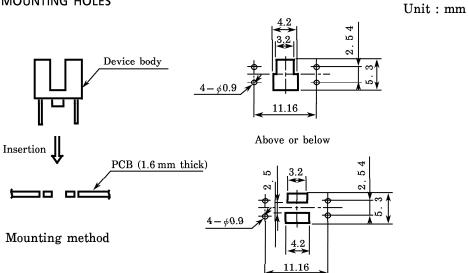








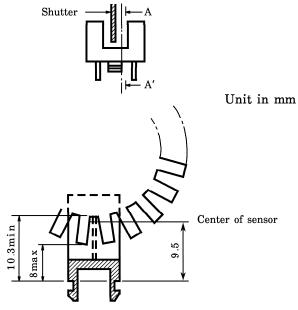
### RECOMMENDED MOUNTING HOLES



Recommended mounting holes

## RELATIVE POSITIONING OF SHUTTER AND DEVICE

For normal operation position the shutter and the device as shown in the figure below. By considering the device's detection direction characteristic and switching time, determine the shutter slit width and pitch.



Cross section between A and A'

#### RESTRICTIONS ON PRODUCT USE

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